

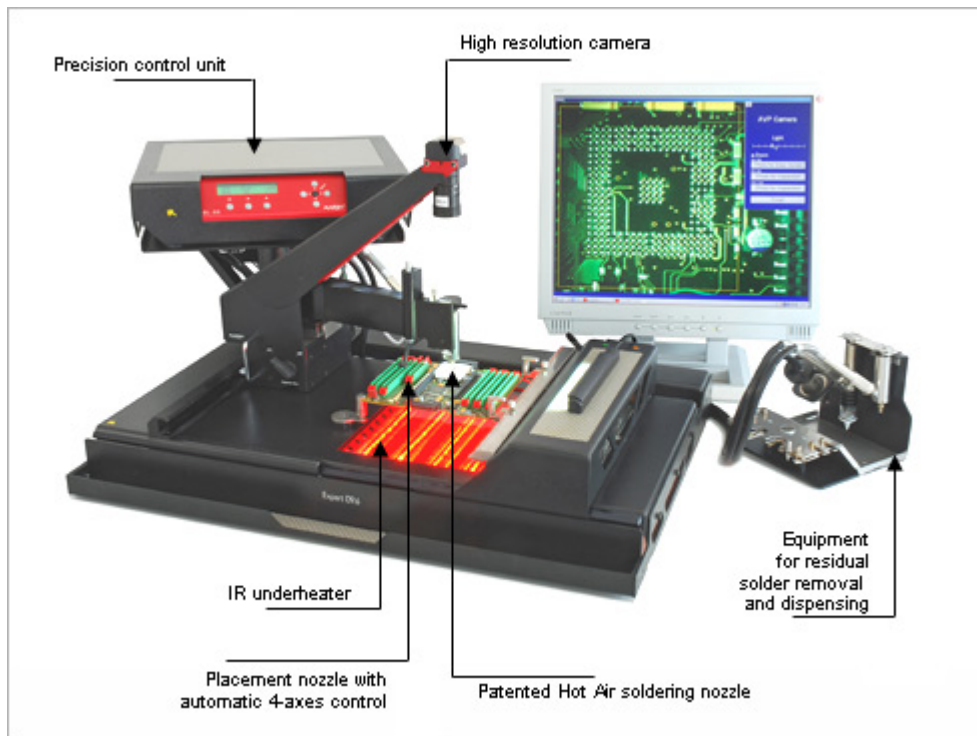
## MARTIN Expert 09.6

Rework Set for all SMD Components



### Rework for Winners

Clear and functional: Standards set by MARTIN. With the intuitive and precise functions of the new Expert 09.6 even demanding processes become easily executable tasks. You too can trust "Made by MARTIN". Reliable solder connections of reworked components are our best advertisement.



#### Well Proven

You can rely on patented Martin Technology. Extensive know-how and eminent precision has been proven thousands of times by our customers around the world for more than 25 years.

#### More Efficient

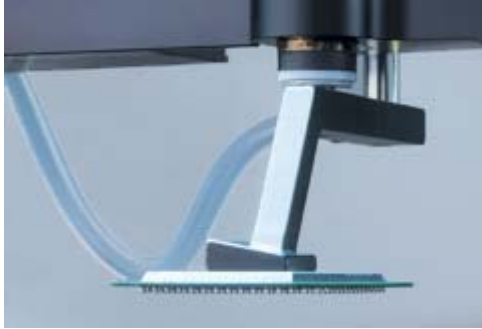
Just profit from the speed of the new MARTIN Expert 09.6. Quick and reliable processes as well as very attractive pricing provide maximum advantage.

### More Flexible

Equip yourself for the demands of tomorrow. Just as its famous predecessors, the new MARTIN Expert 09.6 is future proof and compatible with the smallest SMDs as well as large processor sockets.

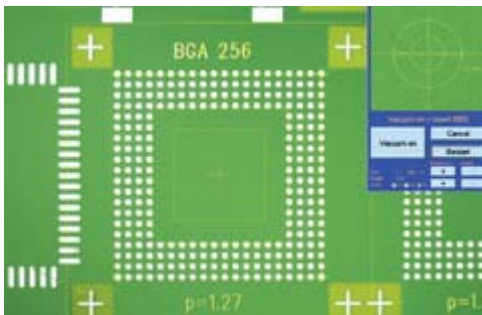


### Your Plus in Placement

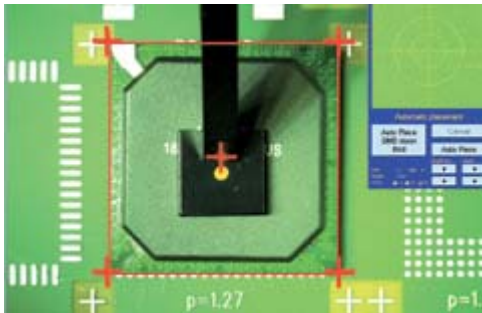


The new MARTIN Expert 09.6 offers absolute certainty and leading edge speed with its patented placement system. The crystal clear, flawless camera checks and controls the automatic placement process, from the first moment to the final error free result.

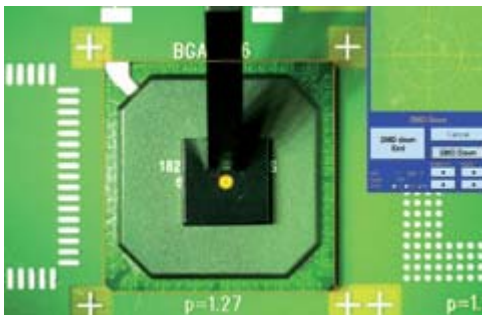
### Automatic and camera controlled



Exact capturing of the pad array with only three mouse clicks.



Generation of SMD coordinates.



Controlled and automatic placement of the SMD onto the pad array.

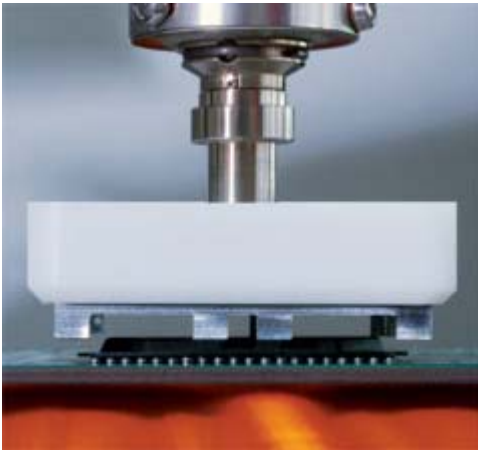
### Auto Vision Technology

Automated SMD placement is simplicity itself for operators: The pads shown on the screen are marked and all coordinates of the component are established with three final mouse clicks. Placement is then controlled in every detail by the camera and carried out automatically by the machine. There is no quicker, more certain or more accurate way of positioning SMDs.



## Your Advantage in Soldering

The new Expert 09.6 employs the highest standards of thermodynamics. PCBs are provided with the required basic heat rapidly, yet carefully from below. At the same time the solder joints are heated precisely for the reflow process. This combination guarantees the best soldering results.

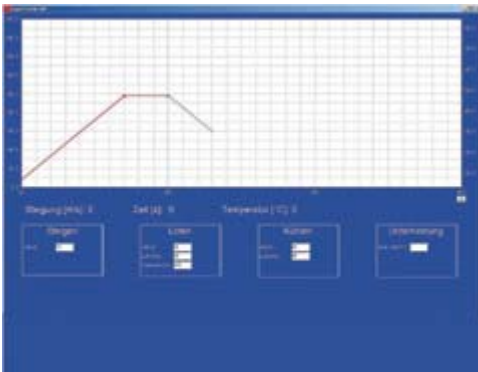


### Precision Hot Air

MARTIN's Precision Hot Air technology ensures that the required soldering temperature is reached without exceeding any maximum value specified for the SMD – within a tolerance of only +/- 1%.

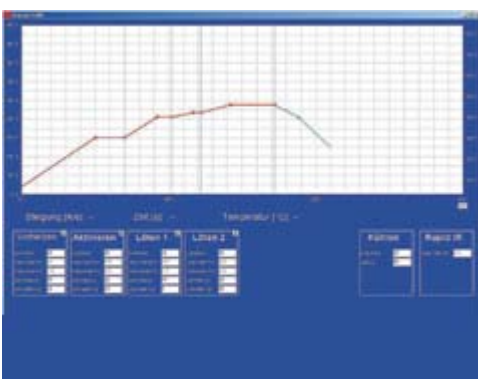
### Rapid Technology

The patented Rapid Technology fully utilises the permitted thermal limits of the PCB. IR underheater and hot air heat at the maximum permitted rate, and after that, maintain temperatures at the recommended level.



### Rapid Profile

Based on Rapid Technology, this innovative profile guarantees a clear and effective process. The result is a time saving up to 30%.

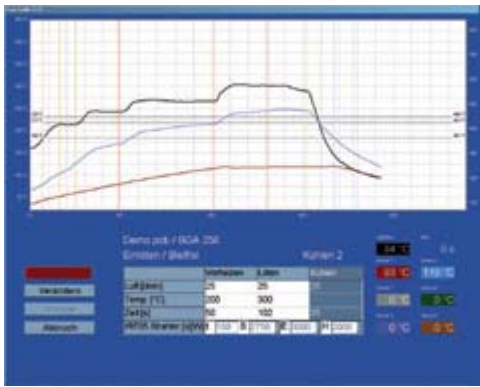


### Diagramm Profile

This module duplicates production reflow oven profiles. Thermal values are simply transferred from a datasheet into the Easy Solder program.

### Classic Profile

Easy Solder software produces a proven 10 phase multi zone profile from just 3 data sets.

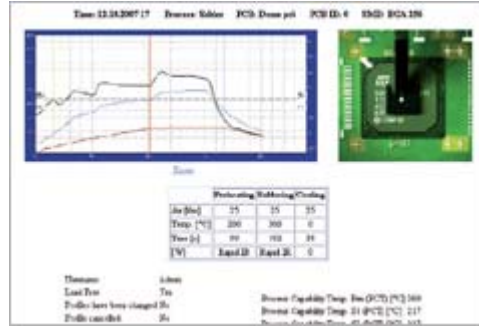


## Extras nach Maß



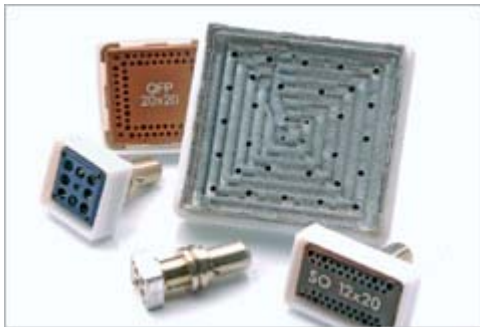
### Micro SMD Set

For the processing of miniature components.



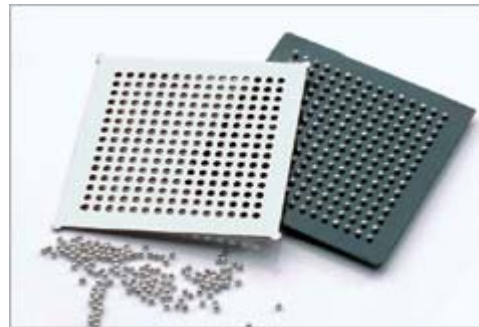
### Report software

Allows access to all stored data of individual solder processes.



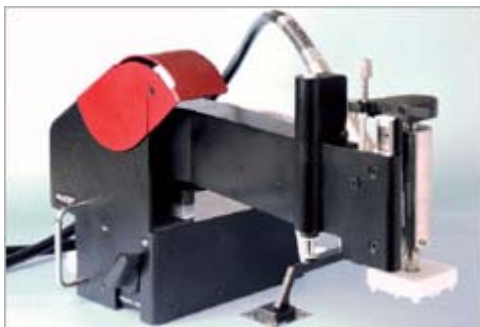
### Soldering nozzles

Sets for all BGAs, CSPs und SOs.



### Reballing Tools

Facilitates the trouble free re use of removed components.



### Expert 07.6

This low-cost alternative can later be upgraded to Expert 09.6.

## Technical Data

Max. PCB width	390 mm
Max. PCB length	500 mm
Footprint	700 x 900 mm
Hot Air	2-35 l/min ± 1 l/min
	50-400°C ± 1,0 % (repeatability)

Underheater	500 - 3000 Watt 250 x 280 mm
WIN software	Easy Solder 06
Travel	75 mm / 75 mm / 23 mm / $\pm 10^\circ$
Resolution of axes	0,001 mm
Resolution of camera	1944 x 2595 Pixel
Image size	14 x 18 mm (Flip Chip) 28 x 37 mm (CSP) 37 x 50 mm (BGA/QFP) 65 x 85 mm (Maxi-BGA)
Placement accuracy	$\pm 0,015$ mm (Flip Chip) $\pm 0,03$ mm (CSP) $\pm 0,04$ mm (BGA/QFP) $\pm 0,07$ mm (Maxi-BGA)



## Ausstattung des Komplett-Sets

- Solder station DBL 05 with soldering pen, tool magazine, reballing holder, 2 soldering nozzles (4.0, 7.0 mm)
- Dis module with dispensing pen, 2 aluminium nozzles (0.3 mm), cleaning set
- Vac module with vacuum pen, 4 placement nozzles (0.7, 1.5, 6.3, 8.5 mm), 2 solder sucker nozzles (1.0, 1.4 mm), cleaner
- Measurement module with ultra fine sensors, 2 channels
- Underheater IRF 04 (3000 W)
- PCB table Smart Fix 06 with hand rest, illumination, cooling, 4 PCB holders and 8 PCB supports
- Auto Vision Placer with 5 automatic axes, camera, 2 lenses and 4 placement nozzles
- Second soldering pen for residual solder removal
- Foot switch, solder paste, solder balls, flux pen, flux cream
- CSP/BGA transfer tool, SMD hook
- Set with 7 soldering nozzles for all PLCCs, QFPs
- Box with consumables
- Rework ABC (handbook)
- MARTIN Rework software Easy Solder 06 (WIN 2000/XP/Vista)